

2020 15th International Microsystems, Packaging, Assembly and Circuits Technology Conference (IMPACT 2020)

**Taipei, Taiwan
21 – 23 October 2020**



**IEEE Catalog Number: CFP2059B-POD
ISBN: 978-1-7281-9852-1**

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|-------------------------|-------------------|
| IEEE Catalog Number: | CFP2059B-POD |
| ISBN (Print-On-Demand): | 978-1-7281-9852-1 |
| ISBN (Online): | 978-1-7281-9851-4 |
| ISSN: | 2150-5934 |

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